

MAINTENANCE MANUAL

138—174 MHz RF ASSEMBLY 19D416693G1, 2 AND MIXER/IF BOARD 19C320153G1

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DESCRIPTION

The RF Assembly uses five tuned helical resonators to provide front end RF selectivity with no gain. A UHS pre-amplifier assembly is available that can be used with the receiver to improve sensitivity.

The Mixer/IF board (MIF) uses the RF signal from the RF Assembly and the mixer injection frequency from the oscillator multiplier board to generate the IF frequency.

CIRCUIT ANALYSIS

RF ASSEMBLY

RF PRE-AMPLIFIER (Optional)

The pre-amplifier is present only in UHS receivers, and uses a dual-gate Field Effect Transistor (FET) to provide approximately 12 dB gain.

RF from the antenna is coupled through T2301 to Gate 1 of pre-amplifier Q2301. The primary of T2301 provides a 50-ohm input impedance. The amplified output at the drain terminal of Q2301 is coupled through T2302 and connected to J1 on Antenna Input board A301 through cable W2302. T2302 is tapped to provide a 50-ohm output impedance. P2301 connects to J501 on the MIF board for the regulated +10 Volt supply voltage.

ANTENNA INPUT A301

An RF signal from the antenna or UHS pre-amplifier is applied to A301 which provides an AC ground between vehicle ground and receiver A-. Resistor R1 prevents a static charge from building up on the vehicle antenna. The output of A301 is coupled through five high Q helical resonators that provide the front end RF selectivity. The helicals are tuned to the incoming frequency by C301 through C305.

MIXER-IF

MIXER & CRYSTAL FILTER

The mixer uses a FET (Q501) as the active device. The FET mixer provides a high input impedance, high power gain, and an output relatively free of harmonics (low in intermodulation products).

In the mixer stage, RF from the helical resonators is coupled through L502 and C502 which matches the RF output to the gate of mixer Q501. Injection voltage from the multiplier-selectivity stages is inductively coupled through L501 to the source of the mixer. The 11.2 MHz mixer IF output signal is coupled from the drain of Q501 through a tuned circuit (L505 and C505) which matches the mixer output to the input of the four-pole monolithic crystal filter. The highly-selective crystal filter (FL501 and FL502) provides the first portion of the receiver IF selectivity. The output of

the filter is coupled through impedance-matching network L520 and C523 to the IF amplifier.

Service Note: Variable capacitor C521 does not require adjustment when performing normal alignment. If the four-pole monolithic crystal filter is replaced, then adjustment of C521 is necessary for optimum IF response.

IF AMPLIFIER

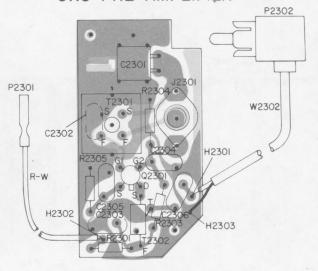
IF amplifier Q520 is a dual-gate FET. The filter output is applied to Gate 1 of

the amplifier, and the output is taken from the drain. The biasing on Gate 2 and the drain load determines the gain of the stage. The amplifier provides approximately 20 dB of IF gain.

The output of Q520 is coupled through impedance matching network L521, and C528 and coupling capacitor C529 and feed-through capacitor C325 to the next IF stage on to the MIF switch in Dual Front End Applications.

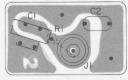
Supply voltage for the RF amplifier and MIF board is supplied through feed-through capacitor C326.

UHS PRE-AMPLIFIER



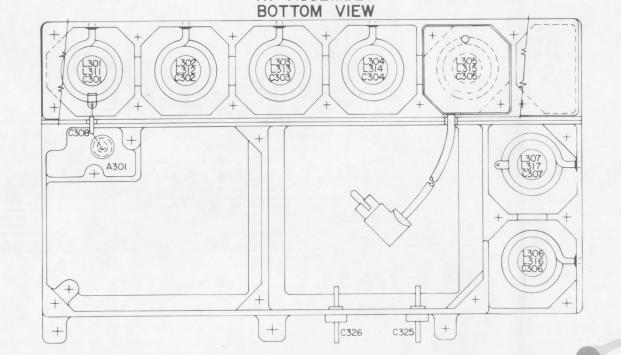
(19C320201, Sh. 2, Rev. 1) (19C320201, Sh. 3, Rev. 1)

A30I ANT INPUT



(19B219679, Sh. 2, Rev. 2

RF ASSEMBLY



RUNS ON SOLDER SIDE

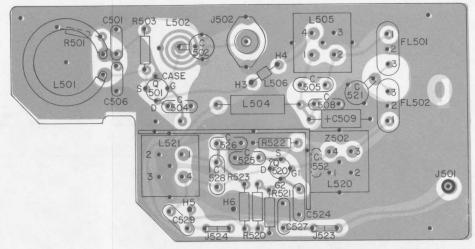
(19D423618, Rev. 1)

RUNS ON BOTH SIDES

RUNS ON COMPONENT SIDE

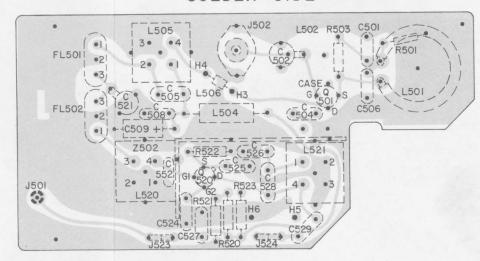
MIXER/IF BOARD

COMPONENT SIDE



(19C321054, Sh. 2, Rev. 1) (19C321054, Sh. 3, Rev. 0)

SOLDER SIDE



(19C321054, Sh. 2, Rev. 1)

FOR Q501 Q520, Q2301

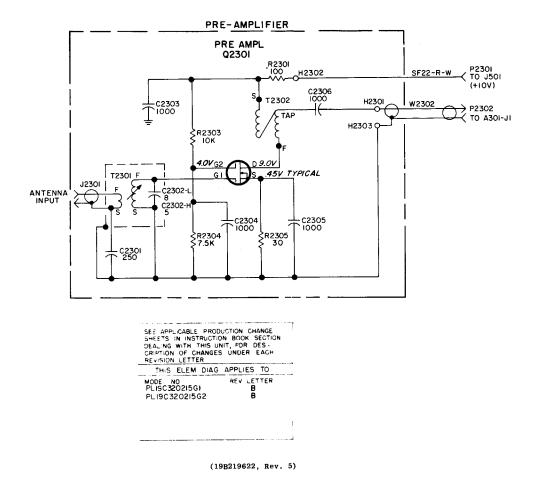
LEAD IDENTIFICATION

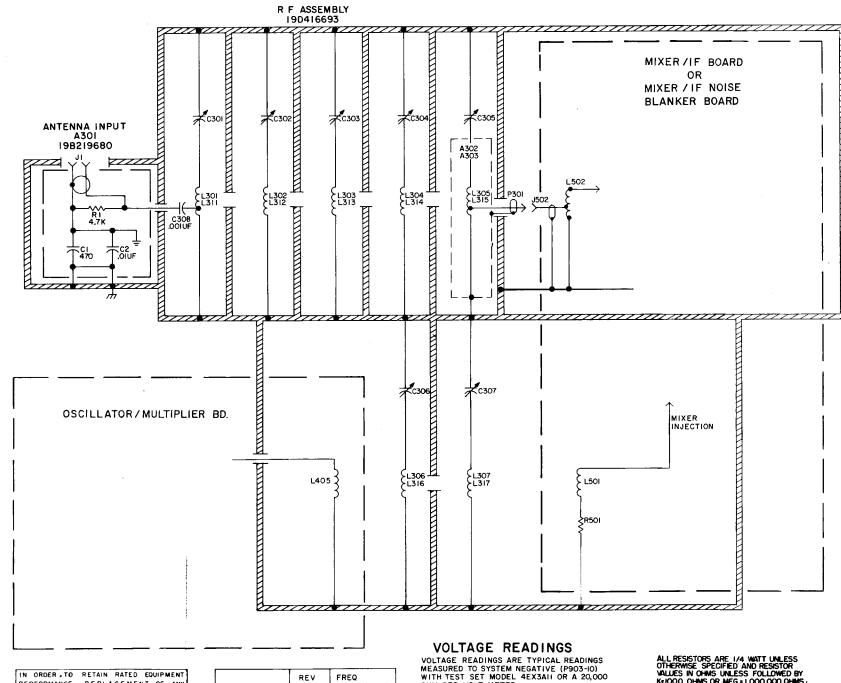
CASE
VIEW FROM CASE END

NOTE: LEAD ARRANGEMENT, AND NOT CASE SHAPE, IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

OUTLINE DIAGRAM

138—174 MHZ RF ASSEMBLY AND MIXER/IF BOARD





PERFORMANCE, REPLACEMENT OF ANY SERVICE PART SHOULD BE MADE ONLY WITH A COMPONENT HAVING THE SPECIFICATIONS SHOWN ON THE PARTS LIST FOR THAT PART.

REV FREQ LETTER RANGE (MHZ) RF ASSEMBLY 19D416693G1 138-155 150.8-174 190416693G2

VOLTAGE READINGS ARE TYPICAL READINGS MEASURED TO SYSTEM NEGATIVE (P903-IO) WITH TEST SET MODEL 4EX3AH OR A 20,000 OHM-PER-VOLT METER.

INDICATES A-

L INDICATES VEHICLE GROUND

ALL RESISTORS ARE 1/4 WATT UNLESS OTHERWISE SPECIFIED AND RESISTOR WALLES IN OHMS UNLESS FOLLOWED BY K+1000 OHMS OR MEG = 1,000,000 OHMS OCAPACITOR VALUES IN PICOPARADS (BRUAL TO MICROMACROFARADS) UNLESS FOLLOWED BY UF = MICROFARADS, INDUCTANCE VALUES IN MICROFARATS, INDUCTANCE VALUES IN MICROFARATS, INDUCTANCE VALUES IN MICROFARMS OR H= HENRYS.

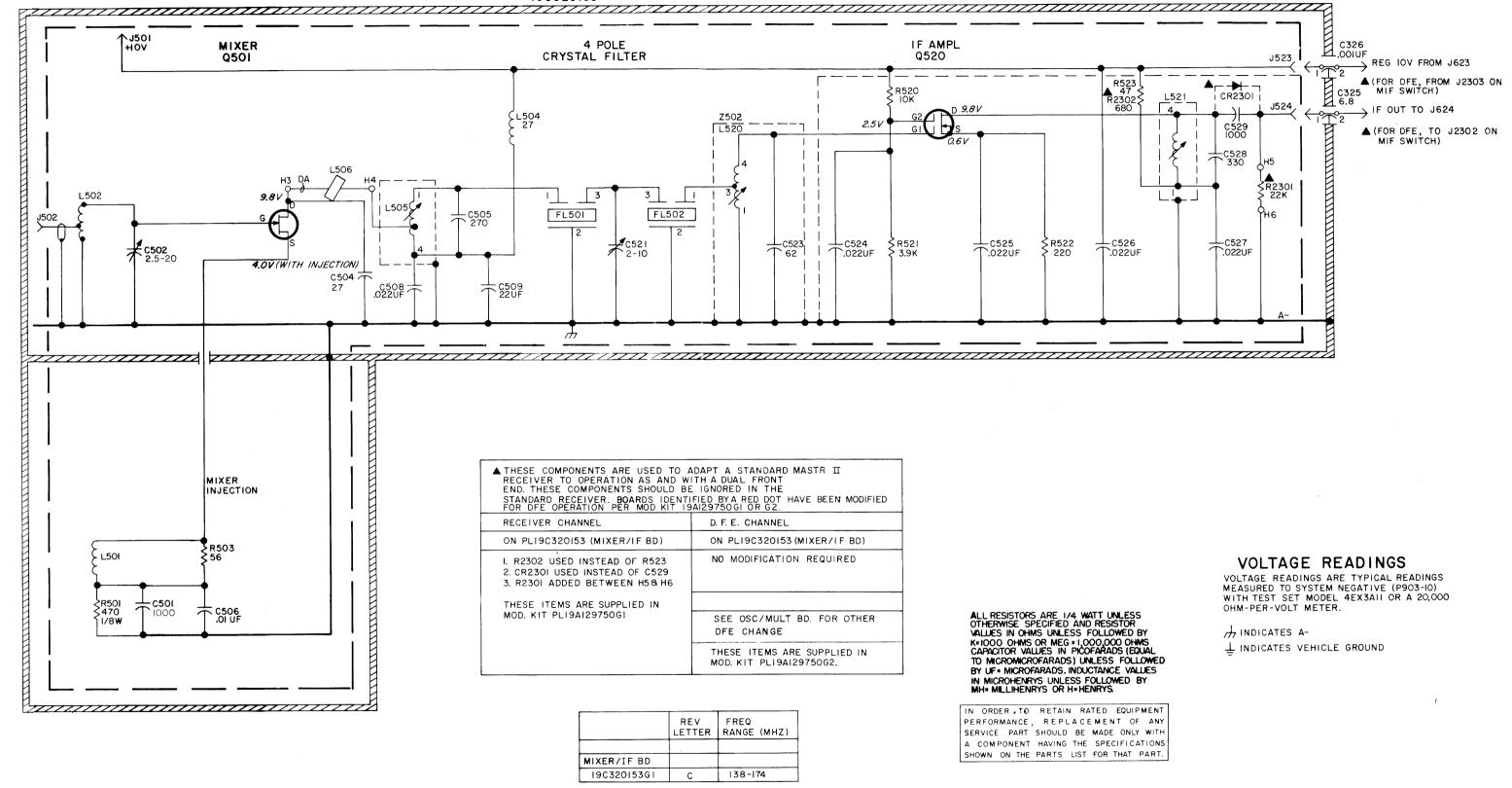
(19D423469, Rev. 0)

SCHEMATIC DIAGRAM

138—174 MHZ RF ASSEMBLY

Issue 1

MIXER/IF BD 19C320153



SCHEMATIC DIAGRAM

138—174 MHZ MIXER/IF BOARD

LBI-4980

PARTS LIST

LBI-4981B

138-174 MHz RF ASSEMBLY, MIF ASSEMBLY, UHS PRE-AMPLIFIER

SYMBOL GE PART N		D. DESCRIPTION				
		RF ASSEMBLY 19D416693G1 138-155 MHz 19D416693G2 150.8-174 MHz				
A301		ANTENNA INPUT BOARD 19B219680G1				
Cl	19A116679P470K	Silver mica: 470 pf ±10%, 250 VDCW.				
C2	19A116080P101	Polyester: 0.01 μf ±10%, 50 VDCW.				
J1	7104941P16	JACKS AND RECEPTACLES Connector, phono: jack; sim to National Tel.				
		Barrel Ceramic.				
		RESISTORS				
Rl	3R152P472K	Composition: 4700 ohms ±10%, 1/4 w.				
4302 and 4303		CCMPONENT BOARD A302 19B226512G1 138-155 MHz A303 19B226512G2 150.8-174 MHz				
L305	19B216112G20	Coil.				
L315	19B216112G21	Coil.				
	į					
P301	5491689P85	Cable, RF: approx 4 inches long, 350 VRMS, 500 VDC operating voltage.				
C301 thru		Includes:				
2305	4036765G11	Screw.				
	7137968P8	Nut, stamped: thd. size No. 6-32; sim to Palnut TO632005.				
2306 and		Includes:				
307	4036765G12	Screw.				
	7137968P8	Nut, stamped: thd size No. 6-32; sim to Palnut T0632005.				
308	5494481P11	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to				
325	19B209488P1	RMC Type JF Discap. Ceramic, feed-thru: 6.8 pf ±20%, 500 VDCW; sim				
326	19B209488P2	to Allen-Bradley Style FA5D. Ceramic, feed-thru: 1000 pf +100% -0%, 500 VDCW;				
		sim to Allen-Bradley Style FA5H.				
.301	19B216112G19					
L302	19B216112G11	Coil.				
thru L304						
L306 ind L307	19B204461G18	Coil.				
L311	19B21611 <i>2</i> G17	Coil.				
L312 thru L314	19B216112G15	Coil.				
L316	19B204461G19	Coil.				

SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.
		MISCELLANEOUS		
	19E500969P1	Casting.	Q501	19A134093P1
	19C320251P1	Cover.	Q520	19A116818P1
	19B209209P305	Tap screw, Phillips POZIDRIV [®] : No. 6-32 x 5/16. (Secures cover).		
	19B201074P304	Tap screw, Phillips POZIDRIV : No. 6-32 x 1/4. (Used with A301-A303).	R501 R503	3R151P471J 3R152P560K
		MIF ASSEMBLY 19C320153G1	R520	3R152P103K
		19032013361	R521	3R152P392K
			R522	3R152P221K
C501	19A116655P19	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.	R523	3R152P470K
0502	19B209351P2	Variable, ceramic: 2.5 to 20 pf, 200 VDCW, temp coef -250 +700 PPM/°C; sim to Matshushita ECV- 1Z-W20P32.	2502	
504	19Al16656P27K0	Ceramic disc: 27 pf ±10%, 500 VDCW, temp coef 0 PPM.	į	
C505	7489162P37	Silver mica: 270 pf $\pm 5\%$, 500 VDCW; sim to Electro Motive Type DM-15.	C523	19A116114P1057
C 5 06	19A116080P101	Polyester: 0.01 µf ±10%, 50 VDCW.		
C508	19A116080P103	Polyester: 0.022 µf ±10%, 50 VDCW.	1.500	10022014174
C509	5496267P10	Tantalum: 22 µf ±20%, 15 VDCW; sim to Sprague Type 150D.	L520	19C320141P4 5493185P9
0521	19B209351P1	Variable: 2 to 10 pf, 200 VDCW, temp coef -350 to +500 PPM/°C; sim to Matshushita ECV- 1ZW10P32.		
C 52 3		(Part of Z502).	l	
524 thru 527	19A116080P3	Polyester: 0.022 μf ±20%, 50 VDCW.		
528	5490008Pl39	Silver mica: 330 pf ±10%, 500 VDCW; sim to Electro Motive Type DM-15.	C2301	19A116795P250K
529	19A116655P19	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to	C2302L	
		RMC Type JF Discap.	С2302Н	
			C2303 thru C2306	19A116655P19
10 ind 11	19B209055P8	Terminal, feed-thru: sim to Electrical Ind. ABAS40WSS.	02300	
			J2301	19A116832P1
FL501	19B219573G3	Crystal, freq: Resonator A: 11,200000 KHz, Resonator B: 11,196024. Resonator A: 11,200000 KHz,	P2301 P2302	4029840P2
		Resonator B: 11,196024.		
FL502		(Part of FL501).		
		JACKS AND RECEPTACLES	Q2301	19A116818P1
J501	4033513P1	Contact, electrical: sim to Bead Chain L93-4.		
1502	19A130924G1	Receptacle, coaxial: sim to Cinch 14H11613.	R2301	3R152P101K
J523 and	19A116975P1	Receptacle, wire spring.	R2303	3R152P103K
J524			R2304	3R152P752J
			R2305	3R152P300J
L501	19A129280P1	Coil.	İ	
L502		Coil. (Part of printed wire board).		
L504	7488079 P4 8	Choke, RF: 27.0 μh $\pm 10\%$, 1.40 ohms DC res max; sim to Jeffers 4422-9K.	T2301L	
L505	19C320141G30	Coil. Includes:		
	5493185P9	Tuning slug.	C4	5496218P308
L506	19A126140P1	Core, toroidal.		
L520	10000014300	(Part of Z502).		
L521	19C320141G6	Coil. Includes: Tuning slug.	Ll	19C320141P25

DL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION
			Т2301Н		COIL ASSEMBLY
	19A134093P1	N Type, field effect; sim to Type 2N4391.			19C320141G21
	19A116818P1	N Channel; sim to Type 3N187.	1		
		RESISTORS	C5	5496218P305	Ceramic disc: 5.0 pf ±0.5 pf. 500 VDCW, temp
	3R151P471J	Composition: 470 ohms ±5%, 1/8 w.			coef -150 PPM.
	3R152P560K	Composition: 56 ohms ±10%, 1/4 w.	ļ		
	3R152P103K	Composition: 10,000 ohms ±10%, 1/4 w.	Ll	19C320141P25	Coil.
	3R152P392K	Composition: 3900 ohms ±10%, 1/4 w.		5493185P9	Tuning slug.
	3R152P221K	Composition: 220 ohms ±10%, 1/4 w.	T2302	19A127108G1	Coil.
	3R152P470K	Composition: 47 ohms ±10%, 1/4 w.			
				5.403.600.705	
		COIL ASSEMBLY	W2302	5491689P85	Cable, RF: approx 4 inches long. (Includes P2302).
		19C320141G20			
	19A116114P1057	Ceramic: 62 pf ±5%, 100 VDCW; temp coef -30 PPM.		19B219470P2	Shield.
				19A129424G1	Can. (Used with L505, L521, Z502 and T2301 on PRE-AMPLIFIER Board).
	19C320141P4	Coil.			
	5493185 P 9	Tuning slug.			
		UHS PRE-AMPLIFIER BOARD 19C320215G1 138-158 MHz 19C320215G2 147-174 MHz			
					·
	19A116795P250K	Mica: 250 pf ±10%, 250 VDCW; sim to Underwood Type J1HF.			
		(Part of T2301L).			
		(Part of T2301H).			
	19A116655P19	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.			
		TAGEG AND THE TAGE		· [
	19A116832P1	JACKS AND RECEPTACLES			
	13411003271	Receptacle, coaxial: sim to Cinch 14H11613.			
	4029840P2	Contact, electrical: sim to Amp 42827-2.			
		(Part of W2302).			
	19A116818P1	N Channel, field effect; sim to Type 3N187.			
ı		RESISTORS			
	3R152P101K	Composition: 100 ohms $\pm 10\%$. 1/4 w.			
	3R152P103K	Composition: 10,000 ohms ±10%, 1/4 w.			
	3R152P752J	Composition: 7500 ohms ±5%, 1/4 w.		·	
- 1	3R152P300J	Composition: 30 ohms ±5%, 1/4 w.			

Ceramic disc: 8.0 pf ± 0.5 pf, 500 VDCW, temp coef -150 PPM.

Coil.

Tuning slug.

*COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES.



PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter", which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

REV. A thru C - Mixer/IF Board 19C320153G1

REV. A and B - RF Assembly 19D416693G1,2

REV. A and B - Preamplifier Assembly 19C320215G1,2

Incorporated in initial shipment.